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(54) Title: COMPOSITION FOR MANUFACTURING SiO₂ RESIST LAYERS AND METHOD OF ITS USE

(57) Abstract: The present invention relates to compositions, which are useful for the generation of patterned or structured SiO₂-layers or of SiO₂-lines during the manufacturing process of semiconductor devices, and which are suitable for the application in inkjet operations. The present invention also relates to a modified process of manufacturing semiconductor devices taking advantage of these new compositions.



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